Chapter 1: Fundamentals of Computer Design (Part 2)

What is computer architecture?

Why study computer architecture?

Common principles

- Performance
  - What is performance: latency, throughput
  - The performance equation
  - Measuring performance
  - Improving performance: parallelism, locality, Amdahl's law
- Power
- Cost
- Reliability

What is Performance?

Two Metrics

- Latency (or response time or execution time)

- Throughput (or bandwidth)

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  - = Rate of task initiation
  - = 1 / (time between task completions)

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Example: Automobile assembly line starts one car per hour and holds 20 cars

- Latency = 20 hours
- Throughput = one car per hour
- Throughput > 1/Latency due to overlap

Performance (Cont.)

Definition: X is n% faster than Y if

$$\frac{\textit{Execution Time}_Y}{\textit{Execution Time}_X} = 1 + \frac{n}{100}$$

Example: X = 1 minute, Y = 2 minutes

X is 100% faster than Y

Key Performance Equation

$$CPU_{time} = \frac{instructions}{program} \; X \; \frac{cycles}{instruction} \; X \; \frac{time}{cycle}$$

Instructions per program (path length)

 ISA and compiler

Cycles per instruction (CPI)

 ISA and organization (e.g., cache misses)

Time per cycle (clock time, cycle time)

 Organization and hardware

Measuring Performance

MIPS, MFLOPS don't mean much

Benchmarks

- Real programs
  - Representative of real workload
  - Only way to characterize performance
  - SPEC89 → SPEC92 → SPEC95 → SPEC CPU2000 → CPU2006 → CPU2017
  - SPECFS, SPECWeb, SPECjbb, SPECvirt_Sc2010, TPC
- Kernels
  - ``Representative'' program fragments
  - Often not representative of full applications
  - EEMBC for embedded systems
- Toy benchmarks and synthetic benchmarks
  - Don't mean much

Improving Performance – Basic Principles

Parallelism

Locality

Focus on common case – Amdahl’s law

*Improving Performance – Basic Principles***

Parallelism

- Pipelining (review next)
- Multiple issue
- Multiprocessors

Locality

Focus on common case – Amdahl’s law

*Improving Performance – Basic Principles***

- Parallelism
    - Pipelining (review next)
    - Multiple issue
    - Multiprocessors
- Locality
    - Caches (review later)
- Focus on common case – Amdahl’s law

Amdahl's Law

(Or why the common case matters most)

Let

$$Speedup = \frac{new\ rate}{old\ rate} = \frac{old\ latency}{new\ latency}$$

Consider an enhancement x that speeds up fraction f_x of a task by S_x

$$Speedup_{overall} = \frac{old\ latency}{new\ latency}$$

$$= \frac{\{(1 - f_x) + (f_x)\} \times old\ latency}{(1 - f_x) \times old\ latency + f_x / S_x \times old\ latency}$$

Amdahl’s law gives

$$Speedup_{overall} = \frac{1}{(1 - f_x) + f_x / S_x}$$

Amdahl's Law, cont.

Example: f_x = 95% and S_x = 1.10

$$Speedup_{overall} = \frac{1}{(1 - 0.95) + (0.95/1.10)} = 1.094$$

Example: f_x = 5% and S_x = 10

$$Speedup_{overall} = \frac{1}{(1 - 0.05) + (0.05/10)} = 1.047$$

Example: f_x = 5% and $S_x = \infty$

$$Speedup_{overall} = \frac{1}{(1 - 0.05) + (0.05/\infty)} = 1.052$$

Amdahl's Law Corollary

Since $S_x \rightarrow \infty$ implies

$$Speedup_{overall} = \frac{1}{(1 - f_x) + (f_x/\infty)}$$

For all real speedups:

$$Speedup_{overall} < \frac{1}{1 - f_x}$$

Example

f_x	$1/(1-f_x)$
1%	1.01
2%	1.02
5%	1.05
10%	1.11
20%	1.25
50%	2.00

Or *make the common case fast*

An application?

Power

Power

Energy

Temperature

Power**

Power = Voltage x Current

Energy = Power x Time

Temperature = Complex function of power, determined by max power drawn (averaged over short intervals)

Power and Energy

Power = Dynamic power + Static power

Energy = Power * Time

Dynamic Power $\propto$ Capacitance * Voltage^2 * Frequency

Static power = Static current * Voltage

*Power and Energy***

Power = Dynamic power + Static power

Energy = Power * Time

Dynamic Power $\propto$ Capacitance * Voltage^2 * Frequency

- Clock gating reduces switching to reduce power
- Reducing voltage reduces power
  - But also requires reducing frequency
  - Increases execution time
  - But reduction in power (and energy) more than increase in time
    - *Dynamic voltage-frequency scaling (DVFS)*

Static power = Static current * Voltage

- Power gating reduces static (and dynamic) power

System strategy for energy: Race-to-halt

New reality: Dark Silicon

Growth in Clock Rate

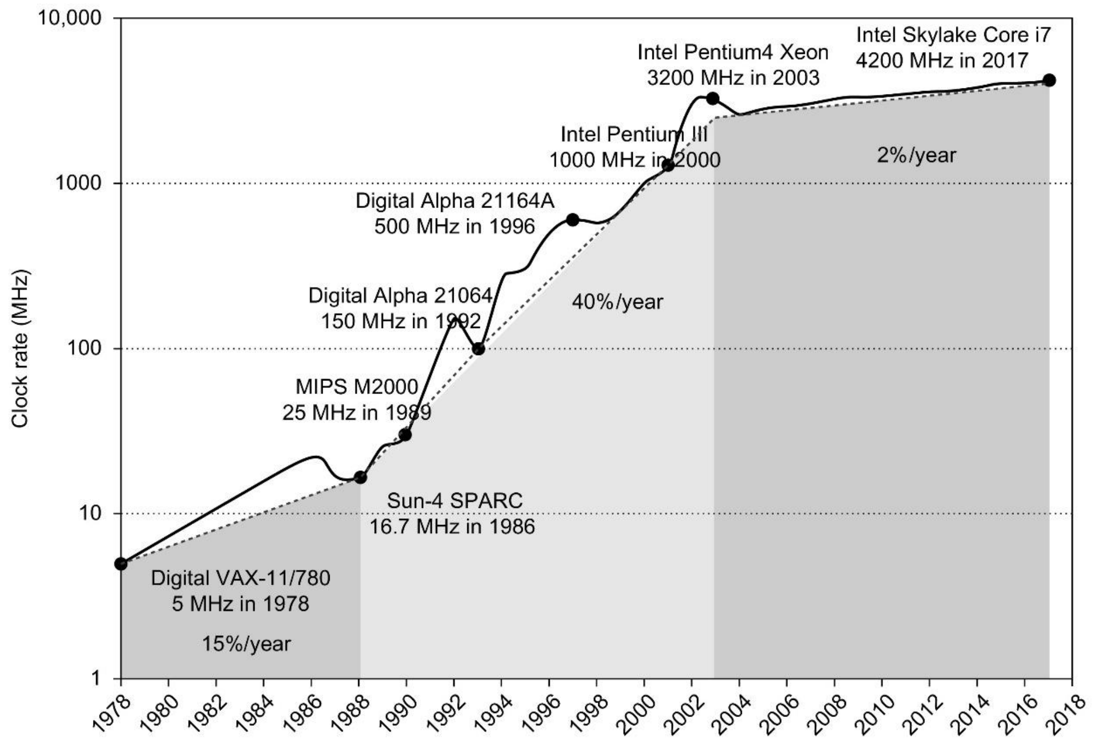

Figure 1.11 Growth in clock rate of microprocessors in Figure 1.1. Between 1978 and 1986, the clock rate improved less than 15% per year while performance improved by 22% per year. During the “renaissance period” of 52% performance improvement per year between 1986 and 2003, clock rates shot up almost 40% per year. Since then, the clock rate has been nearly flat, growing at less than 2% per year, while single processor performance improved recently at just 3.5% per year.

Cost

Cost is very important in most real designs

- But usually hard to quantify for the architect

Costs change over time

- Learning curve lowers manufacturing costs
- Technology improvements lower costs

Focus on IC costs next

A Wafer

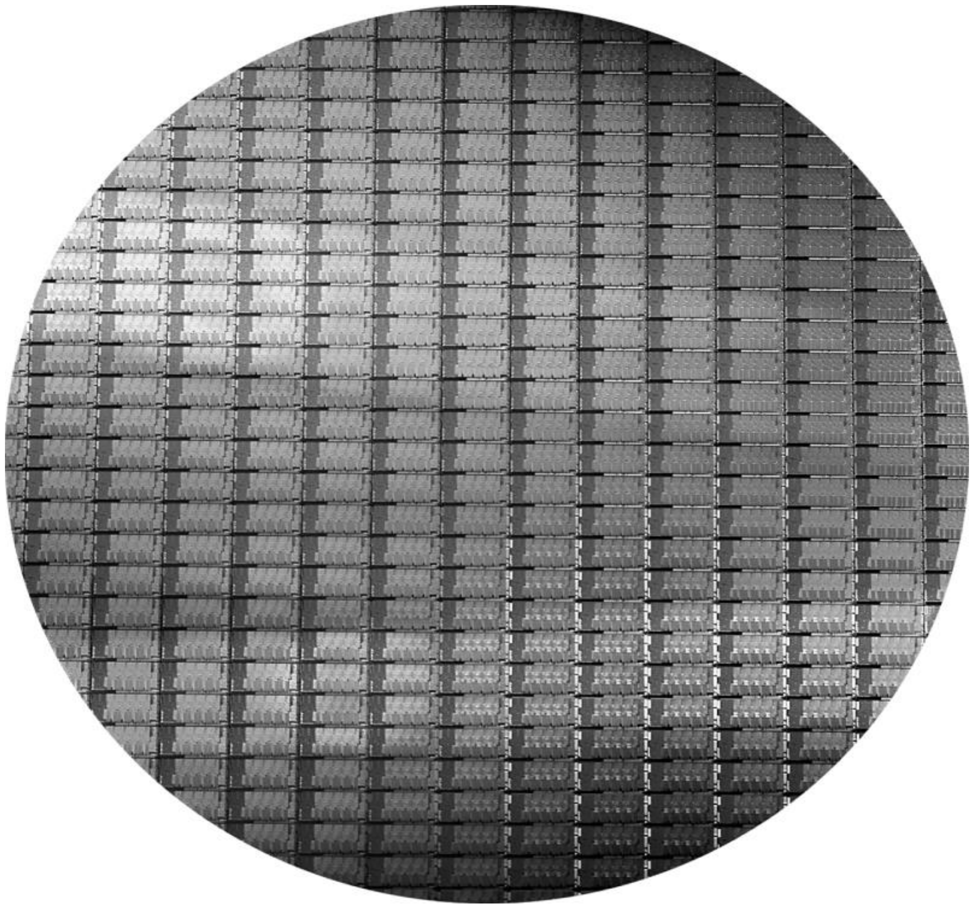

Figure 1.15 This 300 mm wafer contains 280 full Sandy Bridge dies, each 20.7 by 10.5 mm in a 32 nm process. (Sandy Bridge is Intel’s successor to Nehalem used in the Core i7.) At 216 mm2, the formula for dies per wafer estimates 282. (Courtesy Intel.)

A Die

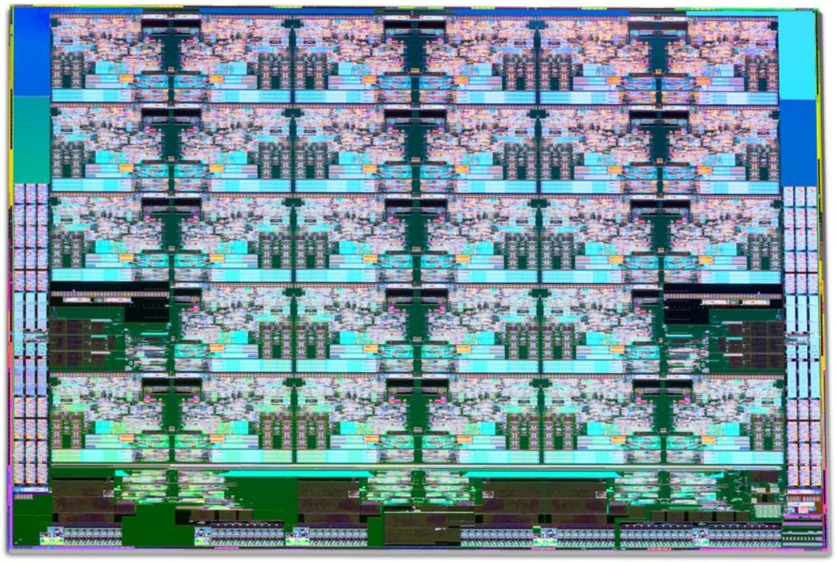

Figure 1.14 Photograph of an Intel Skylake microprocessor die, which is evaluated in Chapter 4.

A Die with Parts Labeled

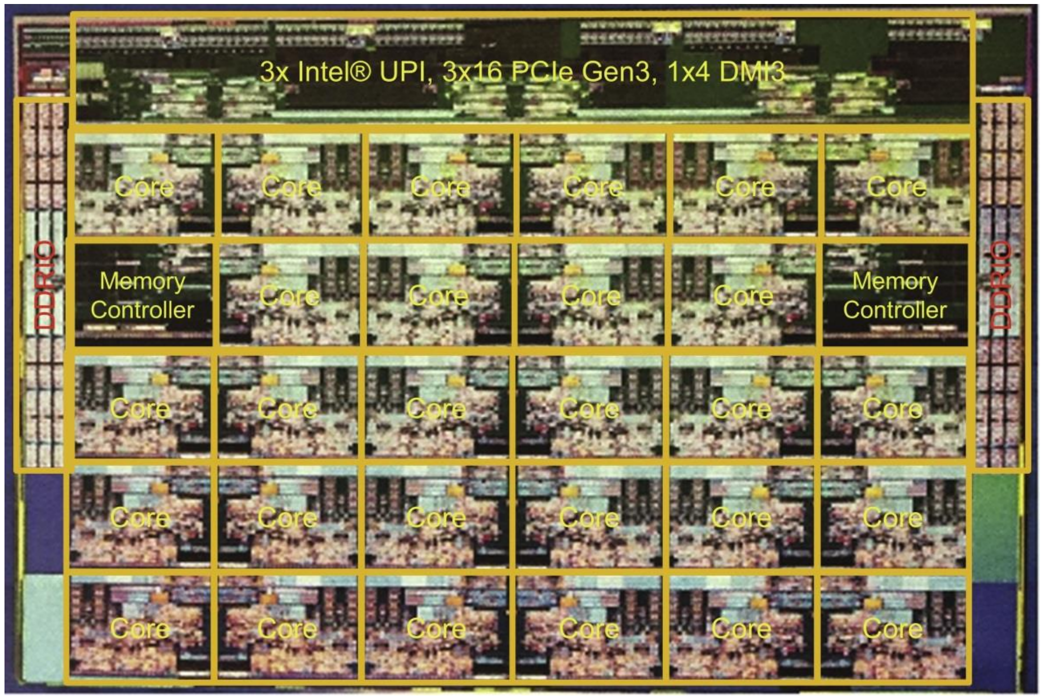

Figure 1.15 The components of the microprocessor die in Figure 1.14 are labeled with their functions.

Integrated Circuit Cost

$$\text{Cost of IC} = \frac{\text{Cost of Die} + \text{Cost of Testing} + \text{Cost of Packaging}}{\text{Final Test Yield}}$$

$$\text{Cost of Die} = \frac{\text{Cost of Wafer}}{\text{Dies per Wafer} \times \text{Die Yield}}$$

$$\text{Dies per Wafer} = \left(\frac{\pi \times (\text{Wafer Diameter}/2)^2}{\text{Die Area}}\right) - (\text{Correction factor for Edge Effects})$$

$$\text{Die Yield} = \text{Wafer Yield} \times \frac{1}{(1 + \text{Defects per unit area} \times \text{Die Area})^{\alpha}}$$

α= 10 to 14 for 16nm in 2017

Bottom line: Cost per die grows roughly as the square of the die area

Cost different from price; cost of manufacturing different from cost of operation

Reliability

- Many sources of unreliability
  - Soft errors due to radiation, hard errors due to wearout, …
- Common metrics
  - Mean time to failure – MTTF
  - For exponentially distributed time to failure
    - Define failures in time or FITs
      - FIT = failures in a billion hours
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      - FIT of system = Sum of FITs of components
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- Common solution
  - Redundancy in time, space, information
  - But must be cheap
    - Many recent innovations